

Hi-Flo 2000

Core Bake Oven flux, Header Dip
flux, Torch and Repair Soldering
Flux

TYPICAL PROPERTIES

Appearance: Mobil Clear Amber
Liquid
Weight: 10.58 LBS/GAL
pH: < 2.0

Description

HI- FLO 2000 provides greater solder penetration. Burns clean thus provides leaner surface resulting in a better core, easier to paint. Better tolerance to open torch heat, reduces charring on parts.

Recommended Application

1

HI- FLO 2000 super concentrate may be applied by a cascade or immersion. Dilution Recommendation Water:Flux Core Bake - 16:1- 20:1. Header Dip - 3:1- 5:1. Torch Soldering - 1:1 - 3:1. Repairs 3:1 - 6:1.

2

It is recommended that the flux residues be removed after soldering operations.

Benefits

- * Used with wide range of solder.
- * Superior cleaning ability for removal of lubricants, shop dirt and oxides.
- * High employee acceptance, no offensive odor.
- * Excellent shelf life.

Health & Safety

Please refer to SDS for complete health and safety information.

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